

Application Data Sheet

Application Information

Application Type::	Regular
Subject Matter::	Utility
CD-ROM or CD-R?::	None
Computer Readable Form (CRF)?::	No
Title::	METHOD OF MANUFACTURING A FLIP-CHIP SEMICONDUCTOR DEVICE WITH A STRESS-ABSORBING LAYER MADE OF THERMOSETTING RESIN
Attorney Docket Number::	067123-0195
Request for Early Publication?::	No
Request for Non-Publication?::	No
Suggested Drawing Figure::	
Total Drawing Sheets::	37
Small Entity?::	No
Petition included?::	No
Secrecy Order in Parent Appl.?::	No

Applicant Information

Applicant Authority Type::	Inventor
Primary Citizenship Country::	Japan
Status::	Full Capacity
Given Name::	Hirokazu
Family Name::	HONDA
City of Residence::	Tokyo
Country of Residence ::	Japan

Street of mailing address:: c/o NEC Corporation
7-1, Shiba 5-chome, Minato-ku
Tokyo,
Country of mailing address:: Japan

Correspondence Information

Correspondence Customer Number:: 22428
E-Mail address:: PTOMailWashington@FoleyLaw.com

Representative Information

Representative Customer Number::	22428	
---	-------	--

Domestic Priority Information

Application::	Continuity Type::	Parent Application::	Parent Filing Date::
This Application	Division of	09/704,521	11/03/2000

Foreign Priority Information

Country::	Application number::	Filing Date::	Priority Claimed::
Japan	11-313684	11/04/1999	Yes

Assignee Information

Assign e nam :: NEC Electronics Corporation